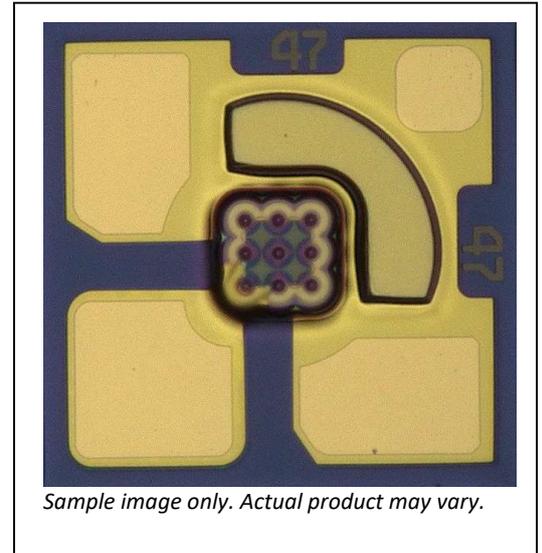


50 Gbit/s VCSEL (940 nm)
High power version
Contact type: SG / GS
Chip type: Multi-aperture

Product Code:

V25-940-SG-MA-HP-C1 1x1

Engineering Samples



Product Description

These compact and very high modulation rate top-emitting GaAs-based vertical cavity surface emitting laser (VCSEL) chips are available as engineering samples for use in the development and evaluation of optical interconnections, optical backplanes and integrated waveguides, and next-generation optical data communications systems. The VCSELs are contacted on the top-surface individually using ground-source-ground (GSG) microprobes or wire bonds.

New multi-aperture design enables high-speed operation at high output power suitable for high-speed sensing and optical wireless applications.

Features

- Up to 56 Gbit/s (PAM4)
- Single chip size 250 x 250 μm
- Suitable for wire bonding

Applications

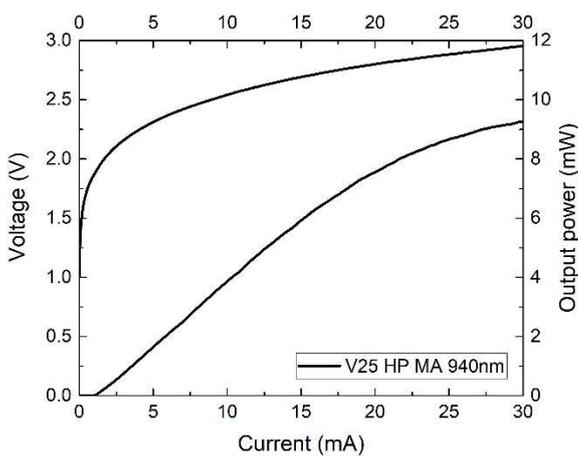
- Sensing
- Optical Wireless
- LiFi

Parameter	Typical	Notes
Emission wavelength	940 nm	(range 930 – 950 nm)
Data rate	Up to 56 Gbit/s	28 GBaud/s PAM-4
RMS	< 0.1 nm	
Peak output power	4 mW	

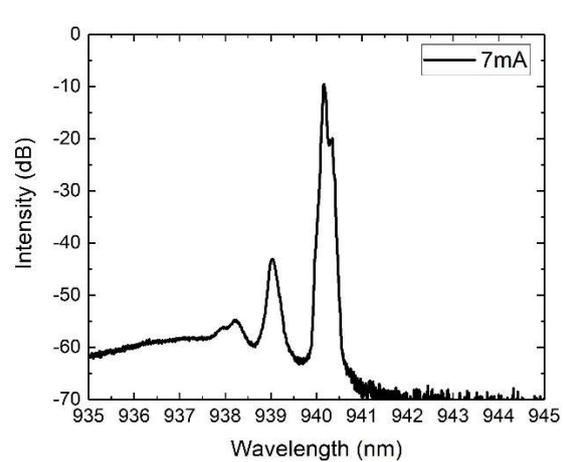
Electro-Optical Specifications (T = 0 to 85°C)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Emission wavelength	λ		930		950	nm
Data rate	BR	PAM-4		50		GBaud/s
Optical bandwidth	BW (f3dBo)	6 mA		18		GHz
Slope efficiency	η	5-10 mA		0.4		W/A
Threshold current	I_{th}				1	mA
Differential resistance	R_d	10-15 mA		30		Ω
Beam divergence	Θ	86%		20		$^\circ$
Peak output power	P_{max}				10	mW
Spectral bandwidth (RMS)	$\Delta\lambda_{RMS}$			0.1	0.3	nm

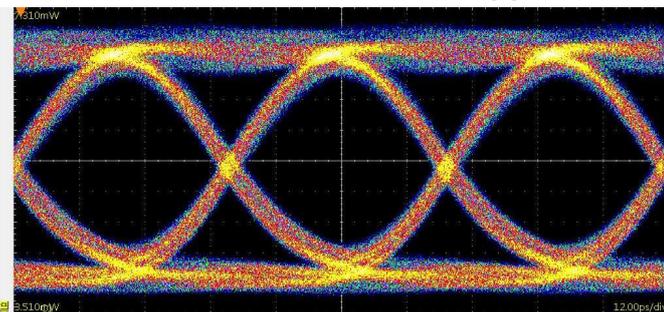
LIV Characteristics



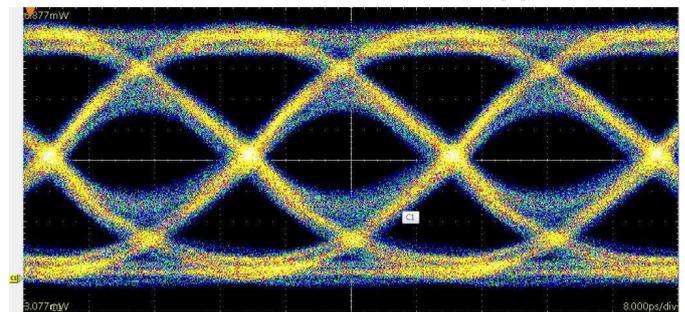
Optical Spectrum



25 Gbit/s NRZ 18 mA 500 mVpp 25°C



40 Gbit/s NRZ 18 mA 400 mVpp 85°C

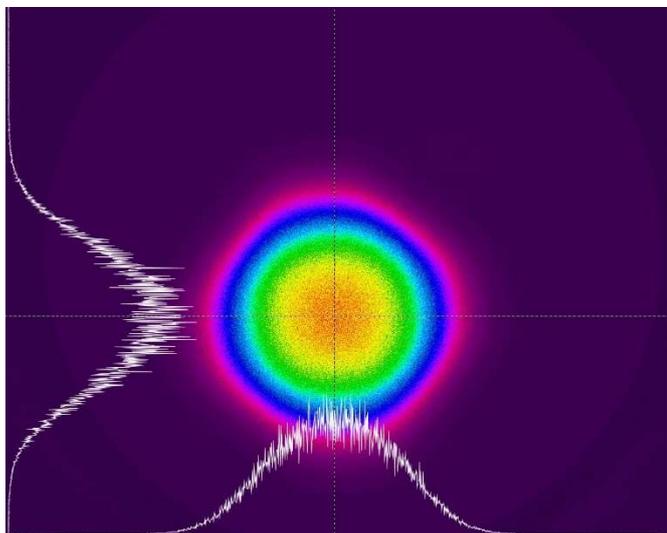


Transmitter: SHF BPG 12104A. Receiver: Tektronix DSA8300 w. 80C15 Optical Sampling Module.

Eye diagrams show intrinsic performance of the chip. No equalization or signal processing was applied.

If the eye-diagram is open at 25Gbaud NRZ without equalization, one can expect good 50Gbit/s PAM4 transmission quality if appropriate PAM driver or/and pre-equalized signal is applied.

Far-field at 15 mA 25°C



Test Equipment: Ophir Photonics Wide Beam Imager

Absolute Maximum Ratings

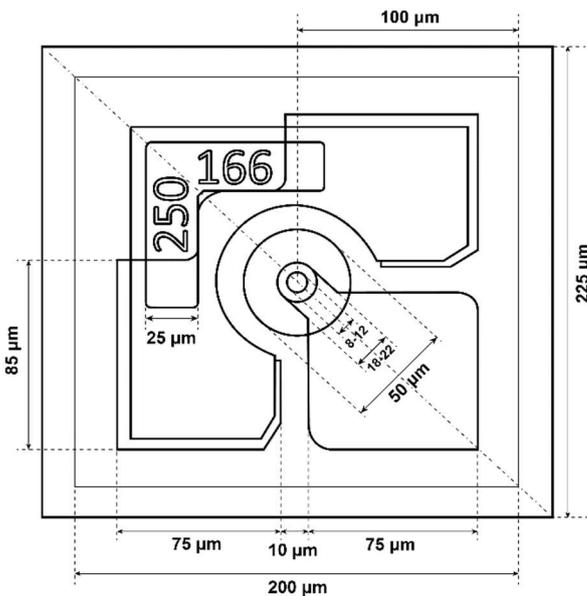
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Peak forward current	I_f				8	mA
Maximum reverse voltage	V_{rv}				5	V
Operating temperature	T_{op}				85	°C
Storage temperature	T_{st}		-40		100	°C
Soldering temperature	T_{sl}	max 260 sec			150	°C

Stress in excess of any of the individual Absolute Maximum Ratings can cause immediate irreversible damage to the component even if all other parameters are within the electro-optical specifications. Exposure to any of the Absolute Maximum Ratings for extended periods can adversely affect the reliability of these chips.

Mechanical Dimensions

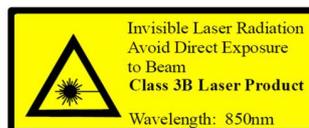
Parameter	Type	Min	Typ	Max	Unit
VCSEL pitch			250		μm
Length			210	250	μm
Height		140	150	160	μm
Width			210	250	μm

Dimensions



Qualification Notification

The V25-940-SG-MA-HP-C1 has been tested to meet specifications outlined in this data sheet at room temperature. However, it has not undergone full qualification testing or characterization and therefore may not meet the performance specifications over all extremes.



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